

ASSIGNMENT RECORDATION FORM COVER SHEET

03-29-1999

To the Honorable Commissioner of Patents and Tr

March 16, 1999

5649.588

Please record the attached original documents or cc

100998224

1. Name of conveying party(ies):

In-Seon Park
Sung-Tae Kim
Du-Hwan Lee
Won-Goo Hur

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Maetan-dong
Paldal-gu, Suwon-city
Kyungki-do, Republic of Korea

JCS42 U.S. PTO
09/270174
03/16/99

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other

Execution Date: July 27, 1998

Additional name(s) & address(es) attached? ☐ Yes ☒ No

09/270,174

03/24/1999 600W16 00000045 09270174

03 7C581 Application Serial No. (40.00 OP)

Patent No.

If this document is being filed together with a new application, the execution date of the application is: March 16, 1999

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

USPTO Customer No. 20792
Mitchell S. Bigel, Esq.
Myers Bigel Sibley & Sajovec
Post Office Box 37428
Raleigh, North Carolina 27627

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number:

DO NOT USE THIS SPACE

9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Scott C. Hatfield, Reg. #38,176
Name of Person Signing

Signature

March 16, 1999
Date

Total number of pages including cover sheet, attachments and document: 3

ASSIGNMENT

THIS ASSIGNMENT, made by us, **In-Seon Park**, a citizen of the Republic of Korea, residing at 440-403, Jukong Apt., Jamsil-dong, Songpa-ku, Seoul, Republic of Korea; **Sung-Tae Kim**, a citizen of the Republic of Korea, residing at 103-208, Samcheonri 2cha Apt., Kwonsun-dong, Kwonsun-ku, Suwon-city, Kyungki-do, Republic of Korea; **Du-Hwan Lee**, a citizen of the Republic of Korea, residing at 104-606 Samik Apt., Poongdukcheon-ri, Sooji-ub, Yongin-shi, Kyungki-do, Republic of Korea; and **Won-Goo Hur**, a citizen of the Republic of Korea, residing at 1211, Cheongsil Apt., 175-8, Gaebong-dong, Kuro-ku, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in **METHODS OF FORMING METAL INTERCONNECTIONS INCLUDING THERMALLY TREATED BARRIER** for which an application for United States Letters Patent has been executed by us concurrently herewith, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, we have hereunto set our hands and seals on this _____ day of _____, 19____.

In Seon Park
In-Seon Park

Sung-tae Kim
Sung-Tae Kim

Du Hwan Lee
Du-Hwan Lee

Won-Goo Hur
Won-Goo Hur

Witnessed by:

Sung H. Lee

Date: 7-27-98

B. J. Bony

Date: July-27-98